

# SOT1967-2

LFBGA486, low profile fine-pitch ball grid array, 486 balls, 0.5 mm pitch, 14 mm x 14 mm x 1.15 mm body

19 March 2018

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LFBGA486
<b>Package style descriptive code</b>	LFBGA (low profile fine-pitch ball grid array)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	1-3-2018
<b>Manufacturer package code</b>	98ASA01210D

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	-	-	14	-	mm
E	package width	-	-	14	-	mm
A	seated height	-	-	1.15	-	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	486	-	A/A



2. Package outline

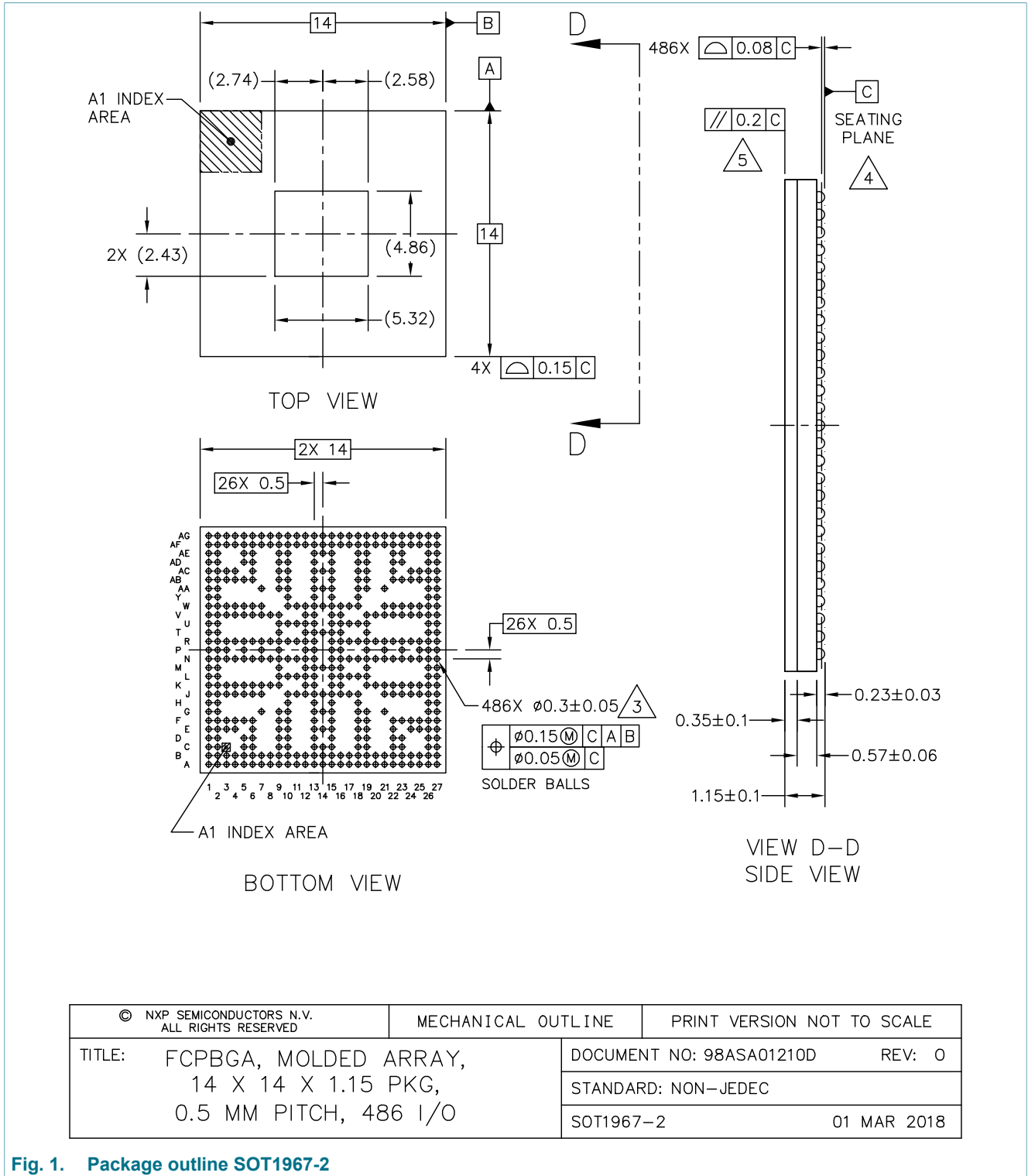


Fig. 1. Package outline SOT1967-2

LFBGA486, low profile fine-pitch ball grid array, 486 balls, 0.5 mm pitch, 14 mm x 14 mm x 1.15 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
4. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
6. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE.

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TITLE: FCPBGA, MOLDED ARRAY, 14 X 14 X 1.15 PKG, 0.5 MM PITCH, 486 I/O	DOCUMENT NO: 98ASA01210D	REV: 0
	STANDARD: NON-JEDEC	
	SOT1967-2	01 MAR 2018

Fig. 2. Package outline note LFBGA486 (SOT1967-2)

### 3. Legal information

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